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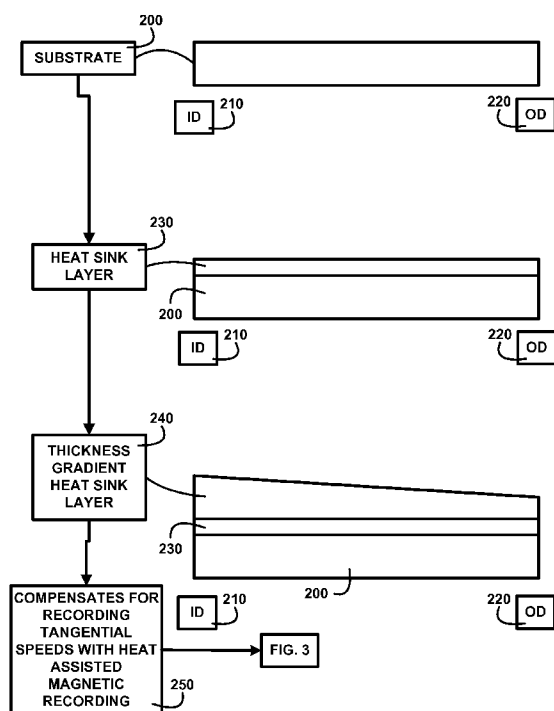


FIG. 2

(57) Abstract: The embodiments disclose a data storage device including a thickness gradient heat sink layer deposited over a heat sink layer deposited over a substrate, a thickness gradient non-magnetic thermal resist layer deposited over the thickness gradient heat sink layer, and a magnetic layer deposited over the thickness gradient non-magnetic thermal resist layer.